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Hardware Manual

SC5309A & SC5310A

2.5 GHz RF Downconverter

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1 General Information

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✓	\checkmark	~	√ (CI((1)))	√	√

A \checkmark indicates that the hazardous substance contained in all of the homogeneous materials for this product is below the limit requirement in SJ/T11363-2006. An X indicates that the particular hazardous substance contained in at least one of the homogeneous materials used for this product is above the limit requirement in SJ/T11363-2006.

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The European Conformity (CE) marking is affixed to products with input of 50 - 1,000 Vac or 75 - 1,500 Vdc and/or for products which may cause or be affected by electromagnetic disturbance. The CE marking symbolizes conformity of the product with the applicable requirements. CE compliance is a manufacturer's self-declaration allowing products to circulate freely within the European Union (EU). SignalCore products meet the essential requirements of Directives 2004/108/EC (EMC) and 2006/95/EC (product safety) and comply with the relevant standards. Standards for Measurement, Control and Laboratory Equipment include EN 61326 and EN 55011 for EMC, and EN 61010-1 for product safety.

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2 Physical Description

2.1 Unpacking

All SignalCore products ship in antistatic packaging (bags) to prevent damage from electrostatic discharge (ESD). Under certain conditions, an ESD event can instantly and permanently damage several of the components found in SignalCore products. Therefore, to avoid damage when handling any SignalCore hardware, you must take the following precautions:

- 1. Ground yourself using a grounding strap or by touching a grounded metal object.
- 2. Touch the antistatic bag to a grounded metal object before removing the hardware from its packaging.



- 3. **NEVER touch exposed signal pins.** Due to the inherent performance degradation caused by ESD protection circuits in the RF path, the device has minimal ESD protection against direct injection of ESD into the RF signal pins.
- 4. When not in use, store all SignalCore products in their original antistatic bags.

Remove the product from its packaging and inspect it for loose components or any signs of damage. Notify SignalCore immediately if the product appears damaged in any way.

2.2 Setting Up the Device

Integration of the SC5309A and SC5310A modules requires attention to maintain effective cooling. Inadequate cooling can cause the temperature inside the RF housing to rise above the maximum for this product, leading to improper performance, reduction of product lifespan, or complete product failure. SignalCore suggests providing moderate airflow across the RF housing. If active cooling is not an option, use thermal interface materials to bond the RF housing to a larger heatsinking surface (i.e. a system enclosure). As each device's integrated system configuration is unique, detailed cooling options cannot be provided.



A cooling plan is sufficient when the SC5309A and SC5310A on-board temperature sensors indicate a rise of no more than 20°C above ambient temperature under normal operating conditions. 2.3 Front Interface Indicators and Connectors

The SC5309A is a PXIe-based RF downconverter with all user I/O located on the front face of the module.





The SC5310A is a serial controlled core module with all user connections on the front face of the module.

2.3.1 Signal Connections

All signal connections (ports) on the device are female SMA-type. Exercise caution when fastening cables to the signal connections. Over-tightening any connection can cause permanent damage to the device.

The condition of your system signal connections can significantly affect measurement accuracy and repeatability. Connections that are improperly mated, dirty, damaged, or worn can degrade measurement performance. Clean out any loose, dry debris from connectors with clean, lowpressure air (available in spray cans from office supply stores).



If deeper cleaning is necessary, use lint-free swabs and isopropyl alcohol to gently clean inside the connector barrel and the external threads. Do not mate connectors until the alcohol has completely evaporated. Excess liquid alcohol trapped inside the connector may degrade measurement performance until fully evaporated (this may take several days).

Tighten all SMA connections with a 3 in-lb min to 5 in-lb max (56 N-cm max)

- **RF In** This is the RF input port to the device with nominal impedance of 50 Ω . Its maximum input power is +27 dBm.
- **IF2 In** This is the input to the second IF stage of the converter. Its nominal input frequency is 1250 MHz.
- **IF Out** This is the IF output of the device with nominal impedance of 50 Ω .
- Ref InThis is the 10 MHz referce input to the device, enabling the device to phase
lock its internal clocks to an external reference source. This nominally 50 Ω
port is AC coupled. Maximum rated input power is +10 dBm.

Ref Out This is the output reference port of the device, allowing for the export of its internal reference clocks. The reference frequency is selectable between 10 MHz or 100 MHz. Typical power level is 3 dBm.

2.3.2 Device LED Indicators

These are LED indicator lights for the device, and their functions are listed in *Table 1* and *Table 2*.

Table 1. Status LED Indicator

LED Color	Description
Green	The device is functioning properly in the state that it is programmed for.
Amber	Indicates that all functions are on standby mode.
Red	Indicates that one or more local oscillators are not functioning correctly.
Off	No supply or supply error.

Table 2. Active Indicator

LED Color	Description
Green	An external interface port has accessed the device.
Red	Input supply voltage exceeded.
Off	No current interface access.

2.3.3 Communication and Supply Connection



Figure 1. Power and Digital IO Connector

Power and communication to the SC5310A is provided through a Molex Milli-Grid^M 2.00mm pitch, 30 position, male header connector. Its part number is 87833-3020. A suggested receptacle female connector is the crimp terminal type 51110-3051 or ribbon type 87568-3093 from Molex. The pin definitions of this I/O connector are listed in *Table 3*.



Pinouts are different for different SignalCore products with the same connector type. Please ensure that mating connectors and cables are wired correctly before connection.

Table 3. Interface connector pin out description

PIN #	Description
1,3,5,7	12V Supply Rail

2,4,6,8,10,12,16,20,24,28	GND
9,11,13,14,15	Reserved, Do Not Connect
17,18	Reserved, pull high to 3.3V or DNC
19	Reset, System reset, logic 0 to reset device
21	Device Active, accessed
22	PLL status
23	RS232 Baud Rate / SPI Mode Select
25	$\overline{\text{CS}}$ Device select for SPI
26	SPI Clock
27	TX/MOSI. TX (DTE) for RS232 or MOSI for SPI
29	RX/MOSE. RX (DTE) for RS232 or MISO for SPI
30	SRDY. This pin is serial ready for SPI



Figure 2. Proper Removal of Latching-Style Ribbon Cable Connectors

2.3.4 Mini-USB Connection



This is a mini-USB Type B connector for USB communication with the device using the standard USB 2.0 protocol (full speed) found on most host computers. The pinout of this connector, viewed from the front, is shown in the following table.

PIN #	USB Function	Description
1	VBUS	Vcc (+5 Volts)
2	D-	Serial Data (neg)
3	D+	Serial Data (pos)
4	ID	Not Used
5	GND	Device Ground (also tied to connector shell)

2.3.5 Reset Button (Pin Hole)

Behind this pin hole is the reset button, which is only available on the SC5310A. Using a pin to lightly depress this momentary-action push button switch will cause a hard reset to the device, putting it back to its default settings. All user settings will be lost. System reset capability can also be accessed through the communication header connector.

3 Functional Description

3.1 Overview

The SC5310A uses USB as its primary interface with an optional SPI or RS232 interface. The SC5309A is a PXIe version of the product.

The downconverter assembly consists of three module parts:

- The Signal Conversion Module contains the mixers, filters, signal amplifiers, and attenuators. This module is referred to as the "signal chain".
- The Synthesized Local Oscillator Module contains the 3 synthesized LO signals and the reference signal circuitry.
- The Power Conditioning and Digital Control Board contains the supply switchers that generate the needs rails for the RF modules and an onboard MCU that provides both the computation engine and interface between the user and the RF modules.



The figure below shows how the modules relate to each other.

Figure 3. Simplified Block Representation of the Downconverter Assembly Module

The downconverter has a maximum of three conversion stages. The first converted intermediate frequency (IF) stage is called IF1, whose signal is converted from the RF input signal. The second converted stage is called IF2, and the third converted stage is IF3. The converted signals in each stage are derived by mixing their respective input signal with their local oscillator (LO) signal. This mixing process results in many products and the desired product at each IF stage is picked out using bandpass filters. Signals that appear inside the passband of the filter will be passed through, while those that are outside the passband are suppressed. Generally, the farther an unwanted signal is away from the filters the better it is suppressed. Unwanted signals that are close to the passband or inside the passband are called spurious signals (or 'spurs' for short). Because of the wide bandwidth of the

IF filters there are input RF frequency regions as well as IF output regions where the number and level of spurs are higher than typical, making those regions unsuitable for high dynamic range applications.

The input tunable range of the downconverter is from ≈ 100 kHz to 2.5 GHz, while the output tunable IF3 range is from ≈ 10 MHz to 100 MHz. The RF is tuned using the first local oscillator (LO1) and IF3 is tuned with LO3. IF3 is tunable from 15 MHz to 140 MHz.

The frequency accuracy and stability of the device is derived from an onboard Temperature Controlled Crystal Oscillator (TCXO) with accuracy better than 500 ppb. For better accuracy and stability, the downconverter can lock to an external reference of higher precision.

3.2 The Signal Chain

The conversion module contains the mixers, filters, amplifiers, and attenuators used to convert, purify, and maintain the amplitude of the signal, all the way from the input of the device to its output. This cascade of signal conversion and conditioning stages is often referred to as the signal chain, which is shown on the system block drawing in *Figure 4*.

3.2.1 The RF Input

All RF connectors are high quality female stainless steel SMA types rated to 18 GHz of operation. The RF port is AC coupled with a 0.1 uF broadband capacitor as indicated in *Figure 4*. The input frequency range at this port is less than 100.0 kHz to greater than 2.5 GHz. The upper limit to which the device tunes to above 2.5 GHz varies slightly from unit to unit depending on the limits of the oscillator circuitry. The usability of the upper out-of-bounds region depends on the roll-off response of the RF elliptic filter and the IF1 mixer.



Figure 4. Block diagram of the signal conversion module of the downconverter assembly

3.2.2 The Input Path Switch

Immediately following the capacitor is an RF switch to selectively direct the RF signal down two paths:

- 1. The default is the conversion path where the RF signal is converted to a final IF.
- 2. The alternative path is directly to the IF port, bypassing all means of frequency conversion. For lower RF frequency that can be digitized directly by a digitizer at the IF port, this path provides the convenience. Another reason for choosing this path for lower frequencies is that converting low RF to an IF may result in more unwanted spurs at the IF output.

When the conversion path is bypassed, the conversion path and the internal LO are disabled by powering down.

3.2.3 The RF Path

The first device in the RF conversion path is a step attenuator with 1 dB step resolution. This attenuator (RF_ATTEN) is used to control the signal level at the mixer or at the RF preamplifier. If the RF level at the input of these devices is relatively large with respect to their input compression points, the signal would experience greater nonlinear effects, distorting its waveform, and producing large spurious 3rd intermodulation distortion effects.

Following RF_ATTEN is a switchable RF amplifier that can be switched into the signal path to improve the device sensitivity, effectively lowering the device noise figure. In other words, the effective input noise level of the device is lowered when this amplifier is enabled. Turning on this amplifier is recommended to improve the signal-to-noise dynamic range (DR_{SNR}) when expected signal levels are lower than -30 dBm. The typical maximum gain of the downconverter without the amplifier enabled is +30 dB. When the amplifier is enabled, its additional +15 dB will boost the typical maximum gain to +45 dB.

The attenuator (RF_ATTEN2) following the amplifier switch is used together with RF_ATTEN1 to control the level at the input of the mixer. Unless the input level is very high, and the attenuation range of RF_ATTEN1 is exhausted, RF_ATTEN2 is not commonly used except when the RF amplifier is enabled. RF_ATTEN1 and RF_ATTEN2 provide 60 dB of attenuation range, which is enough to keep the device in the linear mode of operation even for signal levels near the maximum recommended value of +27 dBm.

Between RF_ATTEN2 and the mixer is the RF elliptic low pass filter. This filter cuts off just above 2.7 GHz and has better than 75 dB of rejection for frequencies above 3.6 GHz. This suppresses back-travel LO leakages to better than -100 dBm (typically -120 dBm) at the input RF port. Another function of this filter is to provide superior suppression of RF image frequencies. The lack of suppression of these RF images could result in mixing with LO1 and appear as spurious components in the IF.

3.2.4 The First Mixer and IF1 Path

The first mixer (IF1 mixer) of the downconverter is very critical as it sets the dynamic ranges of the device for both the signal-to-noise and third order IMD (DR_{IMD}) dynamic ranges. The DR_{SNR} and DR_{IMD} are directly related to the mixer input compression point (IP1dB) and to the input third-order

intercept point (IIP3). The IIP3 of the mixer is typically better than +18 dBm, and its P1dB is better than 5 dBm. In applications that require better signal linearity, it is recommended that the level at the mixer input is kept at -20 dBm or less. Typically, the IMD is better than -75 dBc for two -20 dBm tones at the mixer. Increasing the level at the mixer improves SNR of the IF output signal at the expense of linearity.

Another important characteristic of the mixer is the LO-IF isolation and LO-RF isolation. The higher the isolation, the lower the leakage LO signal is at the RF and IF ports. The IF1 mixer is driven with a \approx +20 dBm LO1 signal and the LO-IF isolation is about 45 dB, resulting in a -25 dBm LO1 leakage in the IF1 path. If the RF signal level at the mixer is -20 dBm and the mixer conversion loss is -8 dB, the converted IF1 signal is -28 dBm. For this case, the LO leakage is greater than the converted IF signal. For most of the RF input range, the LO1 leakage is not an issue because the first IF filter (IF1 BPF) will suppress it. Furthermore, when the leakage passes through the IF2 bandpass filters, it will be further suppressed. However, when the downconverter turns to lower frequency, especially when the RF is near the value of the bandwidth of these filters, the LO1 becomes an unwanted spur.

The frequency relationship between the three ports of the mixer is given as:

LO = IF + RF

As RF approaches 0 Hz, LO -> IF, resulting in the LO leakage being inside the passband of the filter. The filters are not able to optimally reject leakages inside their passband or within their filter slope. This LO1 leakage will mix with the converted IF1 signals or with LO2 to produce higher order unwanted in-band spurs that could be large enough to affect the recovery of signal data. These intermodulation spurs are usually not so easy to determine and deal with. Having high linearity components helps maintain these spurs at acceptable levels. The linearity in these modules keeps these types of 3rd order effects at typically less than -60 dBc. In addition, the LO leakage is a known signal that shows up as the DC value when the final IF spectrum is digitized and processed. For lower RF frequencies it is recommended to switch the RF directly to a digitizer at the IF port instead of putting it through the conversion stages. The user should determine whether the application can tolerate LO leakages, what the effects will be, and decide on the most appropriate route to take.

The first IF (IF1) frequency is centered typically at 3.675 GHz with a minimum bandwidth of 100 MHz. This center frequency may be adjusted programmatically from 3.675 GHz to \pm 50 MHz offset. The default center frequency is set at the factory at the time of calibration to compensate for shifts in the IF1 and IF2 filter responses due to fabrication variations. Another advantage of setting the IF frequency higher is to place it closer to the filter slope region, providing better LO1 leakage suppression.

This stage of conversion is an up conversion rather than a down conversion. This broadband architecture simplifies the input RF and IF1 sections to achieve:

- 1. Superior image rejection without the use of multiple RF bandpass filters.
- 2. Great RF suppression and isolation in the IF2 passband without multiple IF and LO frequency bands.

The disadvantage of this approach is the requirement of high IF1 and LO1 frequencies which places demanding phase noise requirements on the LO1 synthesizer.

3.2.5 The Second Mixer and IF2 Path

The second IF (IF2) is typically centered at 305 MHz and has settable range with 5 MHz steps. The relationship between LO2, IF1, and IF2 is:

$$LO2 = IF1 - IF2$$

IF1 and IF2 are settable with the condition that LO2 must be tuned in 5 MHz steps and have a range less than ± 50 MHz.

The converted IF2 signal out of the mixer is passed through a 500 MHz filter to suppress IF1 and LO2 leakages. The IF2 LPF is not aggressive, so converted LO1 leakages that are close to the IF1 frequency may appear at relatively high values in the IF2 path. After IF2 LPF, the signal passes through the selectable bandpass filters BPF0 and BPF1, whose frequency bandwidths are dependent of the customer option for IF BW. These filters may shape the final BW of the device for low IF frequencies because there are limited filter selections. If there is a need for further signal shaping, an external LPF or BPF will need to be placed after the IF OUT port. This signal will be converted to IF3 via the third IF3 mixer.

For low RF signals, BPF1 can optionally be fitted with a narrow 100 kHz BW filter to suppress LO leakages, especially for those frequencies that are less than the BW of BPF0.

3.2.6 The Third mixer and IF3 Path

The third IF (IF3) is tunable from ± 5 MHz to ± 100 MHz, as LO3 is tuned from 220 MHz to 420 MHz in 5 MHz steps. The negative value of IF3 indicates that the spectrum is inverted with respect to the RF input spectrum. When spectral inversion is selected, LO3 tunes below IF2 and it tunes above for no spectral inversion. There is an LPF filter in this stage to provide filtering of IF2 and LO3 leakages as well as harmonics of the IF3 signal.

Attenuators IF3_ATTEN1 and IF3_ATTEN2 are used to set the output amplitude of IF3. Attenuation should be applied to IF3_ATTEN2 first and any overflow of more than 30 dB is then applied to IF3_ATTEN1. However, if better linearity is needed, apply the first 6 dB to IF3_ATTEN1 and then the rest to IF3_ATTEN2.

3.2.7 Signal Chain Configurations

Recommended signal chain configurations are provided below for various application scenarios. These are strictly recommendations and not indicative of the downconverter function limitations; users will need to adapt the device to their own applications.

3.2.7.1 Low Input RF

If the RF value is on the order of the bandwidth of the narrowest filter, significant LO leakage may appear at the IF output. Placing an external IF filter will provide further suppression of the leakage that appears outside of the passband. If the external digitizer can handle the RF directly, then the RF signal should be switched to the IF port directly, bypassing conversion.

3.2.7.2 Converted Signals

Selecting the narrower filters in the IF2 stage improves the leakage spurs, and allows for lower frequencies at both IF and RF. For example, IF3 could be set to lower for a narrow BW IF2 filter without the risk of possible increase of in-band spurs arising from LO2-LO3 intermodulation or having significant LO leakages even when the device is tuned for RF as low as 5 MHz.

The final IF3 LPF is only a 5th order Chebyshev filter so the rejection slope is not particularly aggressive. This means the harmonic rejection is not as effective for some applications, especially when IF3 is low. It is recommended that an external filter be used to further suppress these harmonics.

3.2.7.3 Dynamic Range Setting

There are 2 sets of digital step attenuators to control the conversion gain of the downconverter. The first set consists of RF_ATTEN1 and RF_ATTEN2 and the second set consists of IF3_ATTEN1 and IF3_ATTEN2. All attenuators, except for IF3_ATTEN2, have 30 dB range and 1 dB step. Attenuator IF3_ATTEN2 has 30 dB range and 0.25 dB step.

To set the downconverter for better sensitivity or better SNR, the gain should be shifted to the RF input path of the device, before the mixer. The RF pre-amplifier should be enabled if necessary and/or RF attenuation reduced. The IF3 attenuator is then used to adjust the final IF output level. The drawback is that the signal level starts off higher as it enters the first mixer as well as the subsequent components. As a result, the apparent linearity of the device is lower.

To set the device for better linearity, the gain should be shifted to the output IF3 path (after the third mixer) and reduced in the RF path. The signal power level at the first mixer should be lower than -20 dB for improved linearity. Since the input signal is low, the relative SNR will be lower. But, as the first mixer and subsequent components experience lower power levels, the apparent linearity of the device is improved.

When the device gain is balanced well, the device can achieve SNR better than 130 dBc/Hz while maintaining IMD3 levels close to 80 dBc. These numbers are representative of converters used in large box high end spectrum analyzers. When the device is optimized for best SNR, typical values better than -150 dBc/Hz can be achieved, and when the device is optimized for sensitivity, the input spectral noise floor is typically lower than -160 dBm/Hz. The flexible use of these attenuators allows the downconverter to achieve better than 190 dB of measurement dynamic range.

3.3 The LO Module

The local oscillator (LO) module contains three local oscillators, the reference clocks, and the calibration EEPROM as shown in *Figure 5*.



Figure 5. Block diagram of the local oscillator

3.3.1 The Reference Clocks

The base clock of the downconverter is a 10 MHz Voltage Controlled Temperature Controlled Crystal Oscillator (VCTCXO) with an initial accuracy better than 500 ppb once the device has reached a stable temperature. Its initial accuracy is set at the factory via an on-board 14-bit voltage reference DAC. This DAC is accessible for dynamic accuracy calibration. The other reference is a 100 MHz Voltage Controlled Crystal Oscillator (VCXO) which is phase locked to the base reference whenever an external reference source is not used.

When an external reference is selected as the base clock by enabling the device to phase lock to it, the effect only occurs when the presence of this reference is detected. In other words, although the device is programmed to lock externally it will not attempt to do so until the reference signal is detected at the input reference port. Notice, both the reference clocks will attempt to lock to the external source. Having the VCXO lock directly to the external source has the advantage of utilizing the close-in phase noise of the source; it is best to assume that the external source is superior to the internal base. Although the internal VCTCXO is not used when an external reference

is selected, it is important to have it remain powered on to maintain its temperature stability. Like the VCXO, it is also phase locked to the external source.

The reference output is derived from the buffered VCXO. When its output is enabled, its frequency can be selected for 10 MHz or 100 MHz. Typically, output power is +3 dBm as its accuracy and stability is that of either the internal VCTCXO or external reference source.

3.3.2 The First Local Oscillator (LO1)

The first local oscillator (LO1) is a YIG based synthesizer tunable between at least 3.3 GHz and more than 6.2 GHz typically. Its multiple hybrid PLL approach gives it the advantages of having lower phase noise, very low spurs, and a small frequency step of 1 Hz. This signal drives the first mixer of the signal chain.

The frequency of LO1 is set indirectly by setting the frequency plan for IF1, IF2, and the RF signal frequency.

3.3.3 The Second Local Oscillator (LO2)

The second LO (LO2) is normally fixed at 3.32 GHz, by it may be set via the frequency plan to tune between 3.1 GHz and 3.45 GHz in 5 MHz frequency steps. LO2 drives the second mixer of the signal chain. Its frequency is indirectly set using frequency plan IF1 and IF2 values using the following relationship:

$$LO2 = step * floor\left(\frac{lF1 - lF2}{step}\right)$$

The ability to tune LO2 allows for the optimization of IF combinations to move higher order intermodulation products that may form inside the passband to outside the passband.

3.3.4 The Third Local Oscillator (LO3)

The third LO (LO3) frequency is set indirectly with IF2 and IF3 frequency values, and the polarity of the IF3 spectrum is set with respect to the RF. IF3 can be set ideally from DC to 100 MHz. When the IF3 spectrum is set to be non-inverted, LO3 tunes from IF2 up to IF2 + 100 MHz, otherwise it tunes from IF2 down to IF2 – 190 MHz. Caution needs to be taken when tuning to the limits because of larger LO leakages and intermodulation products that could form in-band. For example, when the LO3 is set to IF2 - 100 MHz in the inverted case, the IF3 low-pass filters may not sufficiently provide the suppression needed to keep the leakage to an acceptable level at the IF output port. In this case, an external low-pass filter may be needed.

3.4 The Interface Module

Figure 6 shows the power and control interface block for both the SC5309A and SC5310A. All supply rails are produced on board; their voltages are regulated and actively filtered to keep noise to a minimum. Thus, these downconverters are tolerant to "dirty" external power supplies.



Figure 6. Block diagram of the power and interface module.

4 Hardware Registers

The set of hardware registers of the downconverter may be divided into a configuration set and a query set; the configuration registers are write-only registers to set up the states of the device, while the query registers request the device to prepare and send back data associated with them. The registers are identical for all communication interfaces: PXIe, USB, RS232, and SPI. Data communication to all interfaces are sent in 1 byte wide, that is, data is transferred byte-by-byte. Register data lengths vary in size, and it is important that the correct number of bytes are sent for the corresponding register. Failure to do so may cause communication to lock-up and the device to become unresponsive.

4.1 Configuration Registers

These are write-only registers to configure the device. The registers vary in length to reduce redundant data and improve the communication speed, especially for SPI and RS232 interfaces. Furthermore, it is vitally important that the length of data written to a register is exact because failure to do so will cause the interfaces to misinterpret the incoming data, leaving the device in a stalled state. The total number of bytes is the sum of the register address (1 Byte) and its corresponding data bytes. For example, to set the RF frequency value, eight bytes must be written; the sum of the 1 register byte and 7 data bytes. See the RF_FREQUENCY register of Table 4. The table provides a summary of the configuration registers, and each register is explained in detail.

Register Name	Reg Add	Serial Range	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit O
INITIALIZE	0x01	[7:0]	Set to ze	ros [7:1]						Mode
SYSTEM_ACTIVE	0x02	[7:0]	Set to zeros [7:1]							
		[7:0]	Frequency Word (Hz) [7:0]							
		[15:8]	Frequen	cy Word (H	z) [15:8]					
		[23:16]	Frequen	cy Word (H	z) [23:16]					
RF_FREQUENCY	0x10	[31:24]	Frequen	cy Word (H	z) [31:24]					
		[39:32]	Frequency Word (Hz) [39:32]							
		[47:40]	Frequency Word (Hz) [47:40]							
		[55:48]	Set to zeros							LO
	0x11	[7:0]	Frequency Word (Hz) [7:0]							
		[15:8]	Frequency Word (Hz) [15:8]							
		[23:16]	Frequency Word (Hz) [23:16]							
IF_FREQUENCY		[31:24]	Frequency Word (Hz) [31:24]							
		[39:32]	Frequency Word (Hz) [39:32]							
		[47:40]	Frequency Word (Hz) [47:40]							
		[55:48]	Set to zeros							
RF_AMP	0x12	[7:0]	Set to zeros [7:1] Ena							Enable
		[7:0]	0 Attenuator value							
ATTENUATOR	0x13	[15:8]	Set to zeros [15:11] Attenuator Numb						or Number	
		[23:16]	Set to zeros [23:16]							
SIGNAL_PATH	H 0x14	[7:0]	lf3 fil#2 select	lf3 fil#1 s	elect	IF2 filter select	0	Bypass IF3 conv	Ext. IF2 select	Bypass convert
		[15:8]	Set to zeros [15:10] Rf am							invert

Table 4. Configuration Registers

Register Name	Reg Add	Serial Range	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit O	
		[23:16]	Set to zeros [23:16]								
		[7:0]	Set to ze	Set to zeros [7:5] Linear			iode	Auto ctrl amp	Load params	Auto Enable	
CONFIG_AUTO_GAIN	0x15	[15:8]	Sign	Sign Absolute RF level (0 - 127) dB [6:0]							
		[23:16]	Sign	Absolute	e mixer leve	el (0 - 127)	dB [6:0]				
		[31:24]	Sign	Absolute	e IF level (0	- 127) dB	[6:0]				
		[39:32]	Set to ze	Set to zeros							
STORE_DEFAULT_STATE	0x16	[7:0]	Set all to	o zeros							
DEVICE_STANDBY	0x17	[7:0]	Set to ze	eros [7:4]			Device s	ections		Enable	
REFERENCE_CLOCK	0x18	[7:0]	[7:4] set to zeros PXI 10 Clk 100 Ref out enable enable enable				Ref out enable	Lock ext			
		[7:0]	DAC WORD [7:0]								
REFERENCE_DAC	0x19	[15:8]	0	0 DAC WORD [13:8]							
		[23:16]	Set to zeros								
	0x1A	[7:0]	Frequency word (Hz) [7:0]								
		[15:8]	Frequency word (Hz) [15:8]								
		[23:16]	Frequency word (Hz) [23:16]								
FREQ_PLAN_PARAM		[31:24]	Frequency word (Hz) [31:24]								
		[39:32]	Frequency word (Hz) [39:32]								
		[47:40]	Frequency word (Hz) [47:40]								
		[55:48]	Set to zeros [55:52]				PARAM [3:0]				
SYNTH_MODE	Ox1B	[7:0]	Set to ze	eros [7:2]					Loop Ga	ain	
SYNTH_SELF_CAL	0x1C	[7:0]	Set all to	o zeros							
		[7:0]	BYTE DA	TA [7:0]							
USER_EEPROM_WRITE	0x1D	[15:8]	ADDRES	S [7:0]							
		[23:8]	ADDRESS [15:8]								

4.1.1 Register 0x01 INITIALIZE

This register initializes the devices to the default state or reprograms all the device components with the current state parameters. Note, this register does not need to be called in order to program the device.

Bytes written 2 Bytes read 1

Bits	Туре	Name	Width	Description
[0]	WO	Mode	1	0 = Resets the current state 1 = Resets the default to the default or startup state
[7:1]	WO	Unused	7	Set to zeros
[7:0]	RO	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.2 Register 0x02 SYSTEM_ACTIVE

This register turns on or off the active LED indicator on the front connector interface of the device. This register should be called when the device is opened or closed in software.

```
Bytes written 2
Bytes read 1
```

Bits	Туре	Name	Width	Description
[0]	WO	Mode	1	0 = Turns off the active LED 1 = Turns on the active LED
[7:1]	WO	Unused	7	Set to zeros
[7:0]	RO	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.3 Register 0x10 RF_FREQUENCY

This register tunes the device to the input RF frequency.

Bytes written 8 Bytes read 1

Bits	Туре	Name	Width	Description
[47:0]	W	Frequency word	48	Frequency word in milli-Hz (mHz); mHz used for future compatibility
[48]	W	LO	1	Set to 1 to apply value directly to the first LO. The RF frequency value is unchanged.
[55:49]	W	Unused	7	Set to zeros
[7:0]	RO	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.4 Register 0x11 IF_FREQUENCY

This register sets the final IF value.

Bytes written 8 Bytes read 1

Bits	Туре	Name	Width	Description
[47:0]	W	Frequency word	48	Frequency word in milli-Hz (mHz); mHz used for future compatibility
[55:48]	W	Used	8	Set to zeros
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.5 Register 0x12 RF_AMP

This register enables and disables the RF amplifier.

Bytes written 2 Bytes read 1

Bits	Туре	Name	Width	Description
[0]	W	Frequency word	1	0 = Disables the RF amplifier 1 = Enables the RF amplifier
[7:1]	W	Unused	7	Set to zeros
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.6 Register 0x13 ATTENUATOR

This register sets the value of the device attenuators.

```
Bytes written 4
Bytes read 1
```

Bits	Туре	Name	Width	Description
[7:0]	W	Attenuator value	8	In 0.25 dB steps, i.e. LSB = 0.25 dB
[10:8]	W	The target attenuator	3	The attenuator number: 0 = RF Atten #1 1 = RF Atten #2 3 = IF3 Atten #1 4 = IF3 Atten #2
[23:11]	W	Unused	13	Set to zeros

Bits	Туре	Name	Width	Description
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.7 Register 0x14 SIGNAL_PATH

This register configures how the signal chain is routed.

Bytes written 2 Bytes read 1

Bits	Туре	Name	Width	Description
[0]	W	rfPreAmp	1	0 = Turn off RF amp 1 = Turn on RF amp. This parameter is only valid if autogain is off or autogain auto_ctrl_rf_amp is off.
[1]	W	If2Filter	1	0 = Selects the IF2 filter #0 1 = Selects the IF2 filter #1 (custom option)
[2]	W	invertSpectrum	1	0 = Not spectral inversion 1 = IF3 spectrum inverted w.r.t RF
[3]	W	Bypass_rf_conversion	1	0 = RF is converted to IF 1 = RF is directed to the IF port (used for low frequencies)
[7:4]	W	Not used	4	Set to zeros
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.8 Register 0x15 CONFIG_AUTO_GAIN

This register will configure the device to set the attenuator values and control the RF amplifier to keep the device gain close to the desired gain with changes in RF frequency, as computed from its input parameters such as RF input level, mixer level, and IF out level.

Bytes written 6 Bytes read 1

Bits	Туре	Name	Width	Description
[0]	W	autoGain Enable	1	 0 = Attenuator and RF amplifier states are not manipulated when RF values are changed 1 = Computes and applies new sets of attenuator and amplifier states to the device as frequency is changed
[1]	W	loadParams	1	0 = Not to load new input parameter such as RF level, etc. Will not load any information from bits [47:2] 1 = Will load bits [31:2]
[2]	W	autoCntrlRfAmp	1	 0 = Computation will leave the state of the RF amplifier unchanged 1 = Computation will change the state of the RF amplifier to provide the best device configuration to meet the input parameter requirements
[4:3]	W	linearMode	2	 0 = Best signal-to-noise (SNR), least linear 1 = Better SNR, sufficiently linear 2 = Better linearity, sufficient SNR 3 = Best linearity, least SNR
[7:5]	W	Unused	3	Set to zeros
[14:8]	W	rfLevel	7	Set the absolute level of the expected RF input level in dB.
[15]	W	rfLevel Sign bit	1	0 = Positive 1 = Negative
[22:16]	W	mixerLevel	7	Set the absolute level of the expected input mixer level in dB
[23]	W	mixerLevel Sign bit	1	0 = Positive 1 = Negative
[30:24]	W	ifLevel	7	Set the absolute level of the expected output IF3 level in dB
[31]	W	ifLevel Sign bit	1	0 = Positive 1 = Negative
[39:32]	W	Unused	8	Set to zeros

Bits	Туре	Name	Width	Description
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.9 Register 0x16 STORE_DEFAULT_STATE

This register will store all current settings of the device into EEPROM and will become the default startup setting.

Bytes written 2 Bytes read 1

Bits	Туре	Name	Width	Description
[7:0]	W	Unused	8	Set to zeros
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.10 Register 0x17 DEVICE_STANDBY

This register sets either the entire device or sections of the device into standby mode. Placing a section into standby involves powering down its circuitry. This conserves power and eliminates unwanted LO signals when they are not used.

Bytes written 2 Bytes read 1

Bits	Туре	Name	Width	Description
[0]	W	State	1	0 = Active 1 = Standby enabled
[7:4]	W	Unused	4	Set to zeros
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.11 Register 0x18 REFERENCE_CLOCK

This register configures the reference clock behavior.

Bytes written 2 Bytes read 1

Bits	Туре	Name	Width	Description
[0]	W	LockEnable	1	0 = Uses internal 10 MHz TCXO 1 = Enables frequency locking to external 10 MHz reference source
[1]	W	RefOutEnable	1	Reference out port enabled
[2]	W	Clk10Enable	1	0 = 10 MHz output 1 = 100 MHz output
[3]	W	PXI10Enable	1	Only on SC5309A to enable export of the 10 MHz backplane clock
[7:2]	W	Unused	4	Set to zeros
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.12 Register 0x19 REFERENCE_DAC

This register makes adjustments to the 10 MHz TCXO accuracy via DAC to its tuning port.

Bytes written 4 Bytes read 1

Bits	Туре	Name	Width	Description
[15:0]	W	Tuning DAC word	16	DAC WORD
[23:16]	W	Unused	8	Set to zeros
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.13 Register 0x1A FREQ_PLAN_PARAM

This register sets up the frequency plan parameters and stores them as the default values.

Bytes written 8 Bytes read 1

Bits	Туре	Name	Width	Description
[47:0]	W	Data	48	Data for the parameter

Bits	Туре	Name	Width	Description
[50:48]	W	Parameter	3	0 = RF frequency 1 = IF1 frequency 2 = IF2 frequency Filt#0 path 3 = IF2 frequency Filt#1 path 4 = IF3 frequency 5 = LO2 pll step size 6 = LO3 pll step size
[55:51]	W	Unused	5	Set to zeros
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.14 Register 0x1B SYNTH_MODE (2 Bytes)

This register configures the PLL loop gain of the local oscillator synthesizers. It also enables or disables faster tuning of the YIG based oscillator of LO1.

Bytes written 2 Bytes read 1

Bits	Туре	Name	Width	Description
[1:0]	WO	Loop Gain	2	0 = Low loop gain, improves phase noise > 50 kHz 1 = Normal loop gain 2 = High loop gain, improves phase noise < 50 kHz
[7:2]	WO	Unused	5	Set to zeros
[7:0]	RO	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.15 Register 0x1C SYNTH_SELF_CAL

This register will start the YIG synthesizer calibration. Note that although the calibration procedure takes about 6-8 seconds to complete, the register returns a byte almost immediately.

Bytes written 2 Bytes read 1

Bits	Туре	Name	Width	Description
[7:0]	W	Unused	8	Set to zeros

Bits	Туре	Name	Width	Description
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.1.16 Register 0x1D USER_EEPROM_WRITE

This register writes a byte to the onboard EEPROM.

Bytes written 4 Bytes read 1

Bits	Туре	Name	Width	Description
[7:0]	W	Data	8	Byte to be written to the address
[23:8]	W	Address	16	EEPROM address
[7:0]	R	Read back byte	8	Read 1 byte back is required for PXIe and RS232

4.2 Query Registers

These are request for data registers, in that a request for certain data is made by writing to the specific register first, followed by reading back the requested data. Some registers may require instruction data to specify the type of data to return, while others do not need any. For example, the register GET_DEVICE_PARAM (0x30) returns the RF Frequency, IF1 Frequency, IF3 Frequency, etc.; the data returned depends on the parameter value of the instruction byte.

Returned data length is always 8 bytes (64 bits), with the first byte being the most significant (MSB). It is important that all 8 bytes are read to clear the interface buffers. How the different interface buses handle the return data is explained in the *Device Information Parameters and Format* section.

Register Name	Reg Add	Serial Range	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit O
GET_DEVICE_PARAM	0x20	[7:0]		Parameter						
GET_TEMPERATURE	0x21	[7:0]	Zeros [7:0]							
GET_DEVICE_STATUS	0x22	[7:0]	Zeros [7:0]							
GET_DEVICE_INFO	GET_DEVICE_INFO 0x23 [7:0]		Info							
	0.24	[7:0]	EEPROM ADDRESS [7:0]							
CAL_EEPROIVI_READ	UX24	[15:8]	EEPROM ADDRESS [15:8]							
	0.425	[7:0]	EEPROM ADDRESS [7:0]							
USER_EEPROIVI_READ	UX25	[15:8]			EE	PROM AD	DRESS [15	5:8]		

Table 5. Query Registers

Register Name	Reg Add	Serial Range	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit O		
		[7:0]		Zeros [7:0]								
		[15:8]		Zeros [15:8]								
		[23:16]	Zeros [23:16]									
SERIAL_OUT_BUFFER	0x26	[31:24]				Zeros	31:24]					
		[39:32]				Zeros	39:32]					
		[47:40]	Zeros [47:40]									
		[55:48]				Zeros	55:48]					

4.2.1 Register 0x20 GET_DEVICE_PARAM

Write to this register the required device parameter to query from the device.

Bytes written 2 Bytes read 8

Bits	Туре	Name	Width	Description
				0: Returns current RF frequency
				1: Current IF1 frequency
				2: Current IF2 frequency
				3: Current IF3 frequency
[3:0]	W	Parameter	1	4: Current LO1 frequency
				5: Current LO2 frequency
				6: Current LO3 frequency
				7: Current attenuator values
				8: Current signalchain configuration
[7:4]	W	Unused	4	Set to zeros
[63:0]	R	Read back bytes	64	Returned Data (See Device Parameter Data section for more info)

4.2.2 Register 0x21 GET_TEMPERATURE

Write to this register to query the device temperature.

Bytes written 2 Bytes read 8

Bits	Туре	Name	Width	Description
[7:0]	W	Unused	7	Set to zeros
[31:0]	R	Temperature Data	32	These 32 bits of data need to be type casted back to float. i.e. var_float = *(float*)&var_u32 where var_u32 is some unsigned integer that holds the 32 bits of read data.
[63:32]	R	Invalid data	32	Ignore

4.2.3 Register 0x22 GET_DEVICE_STATUS

Write to this register to query the current operating conditions.

Bytes written 2 Bytes read 8

Bits	Туре	Name	Width	Description
[7:0]	W	Unused	7	Set to zeros
[0]	R	Pll status: LO1 sum	1	The summing PLL of LO1
[1]	R	Pll status: LO1 crs	1	The coarse tuning PLL of LO1
[2]	R	Pll status: LO1 fine	1	The fine tuning PLL of LO1
[3]	R	Pll status: LO2	1	LO2
[4]	R	Pll Status: LO3	1	LO3
[5]	R	Pll status: VCXO	1	100 MHz OCXO
[6]	R	Pll status: TCXO	1	TCXO, only valid when lock to external reference is enabled
[7]	R	Pll status: ref_detect	1	Detected a reference signal of sufficient amplitude
[8]	R	Device Accessed	1	When the SET SYS ACTIVE register is accessed
[9]	R	LockExtRef	1	Enable device to lock to external reference
[10]	R	RefOutEnable	1	Reference output enable

Bits	Туре	Name	Width	Description
[11]	R	RefOutFreqSelect	1	10MHz(0) or 100MHz(1) selected as output reference frequency
[12]	R	loopGain	2	Pll loop gain: 0 = Low 1 = Normal 2 = High
[14]	R	IF2FilterSelect	1	IF2 filters: 0 = filt#0 1 = filt#1
[16]	R	Device standby	1	0 = Device off standby 1 = Device in standby mode
[17]	R	rfAmpEnable	1	RF amplifier is enabled
[18]	R	autoRfAmp	1	Auto set the RF preamplifier when autoGainEnable = 1
[19]	R	autoGain Enable	1	Auto calc of gain enabled (default 0). Software gain calculation used. 1 = Gain can be read back from device (less accurate)
[63:20]	R	Invalid data	29	Ignore

4.2.4 Register 0x23 GET_DEVICE_INFO

Write to this register to query the device information such as serial number.

Bytes written 2 Bytes read 8

Bits	Туре	Name	Width	Description
[3:0]	W	DeviceInfo	4	0: Product serial number and Interface type1: Firmware and hardware revision2: Calibration and manufacture date
[7:4]	W	Unused	4	Ignore
[63:0]	R	Data	64	Information data (see Device Info data)

4.2.5 Register 0x24 CAL_EEPROM_READ

Write to this register to query 8 bytes of data from the user EEPROM at the starting address.

Bytes written 4 Bytes read 8

Bits	Туре	Name	Width	Description
[15:0]	W	Address	16	Starting EEPROM address
[23:16]	W	Unused	8	Zeros
[63:0]	R	Data	64	8 bytes of data, LSB is the byte at the start address

4.2.6 Register 0x25 USER_EEPROM_READ

Write to this register to query 8 bytes of data from the user EEPROM at the starting address.

Bytes written 4 Bytes read 8

Bits	Туре	Name	Width	Description
[15:0]	W	Address	16	Starting EEPROM address
[23:16]	W	Unused	8	Zeros
[63:0]	R	Data	64	8 bytes of data, LSB is the byte at the start address

4.2.7 Register 0x26 SERIAL_OUT_BUFFER

Writing to this register only provides the 64 clock edges (Reg + 7 data bytes) to transfer serial data from the device through SPI. Other interfaces do not use this register.

Bytes read 8

Bits	Туре	Name	Width	Description
[55:0]	W	Unused	56	Zeros, just to provide clocking for SPI data from device
[63:0]	R	Data	64	8 bytes of data

4.2.8 Device Parameters Data and Format

The data read back from the GET_DEVICE_PARAM register has a total of 8 bytes, however not all bytes contain valid data. The table below shows the valid data for each of the parameters.

Device Parameter Name	Param num	Data type	Byte 7	Byte 6	Byte 5	Byte 4	Byte 3	Byte 2	Byte 1	Byte O
RF FREQ	0	U64	zeros	Data						
IF1 FREQ	1	U64	zeros	Data						
IF2 FREQ	2	U64	zeros	Data						
IF3 FREQ	3	U64	zeros	Data						
LO1 FREQ	4	U64	zeros	Data						
LO2 FREQ	5	U64	zeros	Data						
LO3 FREQ	6	U64	zeros	Data						
ATTEN VALUES	7	8xU8	zeros	NA	NA	NA	RF A1	RF A2	IF3 A1	IF3 A2
CHAIN CONFIG	8	2xU16	zeros	zeros zeros zeros SC Gain SC Config			onfig			

Table 6. Device parameter data

4.2.8.1 *Frequency parameter values*

Frequency parameter values are returned in the first 7 bytes with the last byte padded with zeros. The least significant bit (LSB) is 1/1000 Hertz (the data is returned in 1 one thousandth of a Hertz). Divide the data by 1000 to obtain the result in Hertz.

4.2.8.2 Attenuator values

Each attenuator value is returned as one byte and the LSB is in 0.25 dB. Divide each byte by 4 to obtain the result in dB.

4.2.8.3 Signal Chain Configuration

The signal chain configuration data is in the first 2 bytes, and their data is represented in the following table.

Table 7. Signa	l chain confi	guration data	representation
----------------	---------------	---------------	----------------

Bit	Description
[0]	RF preamplifier state
[1]	IF spectral inversion
[2]	IF2 filter selection
[7:3]	NA

The first order computed gain (device approx.) of the device is returned in bytes 3 and 4. Data bits [14:0] represent the absolute value in 1/100 of a dB, while bit [15] is the sign bit.

4.2.9 Device Information Parameters and Format

Not all the 8 bytes read back contain valid data. The following table shows the valid bytes of data for each of the parameters.

Device Parameter Name	Param num	Data type	Byte 7	Byte 6	Byte 5	Byte 4	Byte 3	Byte 2	Byte 1	Byte 0
INTERFACE	0	U32				Intrfce		Serial N	lumber	
REVISIONS	1	F32		Software revision				Firmware	e revision	
DATES	2	U32	Mfg	year	Month	Day	Cal	year	Month	Day

4.2.9.1 Interface Information

The first 4 bytes contain the device serial number as an unsigned 32-bit integer. Byte [4] contains the interface as represented in the following table.

Table 8. Interface ID

Bit	Description
[0]	PXI/PXIe
[1]	USB
[2]	SPI
[3]	RS232
[7:4]	Undefined

4.2.9.2 *Revision Information*

The first 4 bytes represent the hardware revision and the last 4 bytes represent the firmware revision of the device. These 4 bytes encompass a 32-bit floating point number so the data needs to be type casted from an unsigned 32-bit value to float value.

4.2.9.3 Date Information

The first 4 bytes represent the manufactured date and the last 4 bytes represent the last calibration date. The date format is outlined in the following table.

Bit	Туре	Description
[0]	U8	Day
[1]	U8	Month
[4:3]	U16	Year (i.e. 2016)

Section 2

Communication Interfaces and Calibration

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5 Communication Interfaces

The SC5309A has a PXI express interface, while the SC5310A has 2 communication interfaces:

- 1. USB and SPI
- 2. USB and RS232

This section will examine the communication aspects of the product, focusing on data transfer to and from the device on each interface. Although the registers are identical for all interfaces, there are subtle differences in the implementation of the interfaces to transfer the data.

5.1 Communication Data Format

All data sent and received by all interfaces is sent as buffers of unsigned bytes. For example, to change RF frequency of the device to 2.5 GHz we perform the following:

- 1. Frequency is sent in 1000th of Hertz, so the data that represents the frequency is 2,500,000,000,000 milli-Hertz.
- 2. This number can be represented by a 64-bit unsigned long, and in Hexadecimal is 0x 0000 0574 FBDE 6000. Only the least 6 bytes are needed to represent all frequencies allowable for this device.
- 3. A byte data buffer needs to be 8 bytes for register RF_FREQUENCY (address 0x10), so the byte array buffer to be sent would be:

[0x10][0x00][0x05][0x74][0xFB][0xDE][0x60][0x00]

The register address byte [0x10] is the first member of the buffer to be sent.

5.2 USB Interface

There are 2 transfer types for the USB interface.

- Control transfer
- Bulk transfer

5.2.1 Control Transfer

The USB control transfer parameters are:

ENDPOINT_IN	0x80
ENDPOINT_OUT	0x00
TYPE_VENDOR	0x40
RECIP_INTERFACE	0x01

5.2.2 Bulk Transfer

The USB bulk transfer parameters are:

ENDPOINT	_IN	0x83
ENDPOINT	OUT	0x04

The bulk transfer from the host to the device operates on a loopback with a data buffer of 8 bytes. When a device register is addressed, and upon completion of the register task, such as changing frequency, it will send back 8 bytes, which the host must read to clear the transfer buffers. Unlike the other interface methods, where only the required number of bytes needs to be sent for a given register, 8 bytes are needed for every USB bulk transfer. For example, if a configuration register requires only 4 bytes to be sent, these bytes will be the first of the 8 bytes and the last 4 bytes are zeros. The returned 8 bytes do not carry valid data for a configuration register. However, they do carry valid data for query registers.

5.3 SPI Interface

The SPI interface on the device is implemented using an 8-bit (single Byte) buffer for both the input and output, hence, it needs to be read and cleared by the device before consecutive bytes can be transferred to and from it. The process of clearing the SPI buffer and decisively moving it into the appropriate register takes CPU time, so a time delay is required between consecutive bytes written to or read from the device by the host. The chip-select pin (\overline{CS}) must be asserted low before data is clocked in or out of the product. Furthermore, pin \overline{CS} must be asserted low for the entire duration of a register transfer.

Once a full transfer has been received, the device will proceed to process the command and deassert low the SRDY pin. The status of this pin may be monitored by the host because when it is deasserted low, the device will ignore any incoming data. The device SPI is ready when the previous command is fully processed and the SRDY pin is re-asserted high. It is important that the host either monitors the SRDY pin or waits for 500 μs between register writes.

There are 2 SPI modes: 0 and 1. The default mode is 1, where data is clocked in and out of the device on the falling edge of the clock signal. In mode 0, data is clocked in and out on the rising edge. To select mode 0, pin 23 of the interface connector must be pulled low to ground as the device is powered on or as the reset line (pin 19) is toggled low-high. If pin 23 is pulled high or left unconnected, mode 1 is selected.



Figure 7. SPI Mode 1 shown.

Register writes are accomplished in a single write operation. Register lengths vary depending on the register. They vary in lengths of 2 to 8 bytes, with the first byte sent being the register address followed by the data associated with that register. The (\overline{CS}) pin must be asserted low for a minimum period of 1 μ s (T_s , see *Figure 8*) before data is clocked in, and must remain low for the entire register write. The clock rate may be as high as 5.0 MHz ($T_c = 0.2 \ \mu s$), however, if the external SPI signals do not have sufficient integrity due to trace issues, the rate should be lowered.



Figure 8. SPI timing.

As mentioned above, the SPI architecture limits the byte rate since after every byte transfer the input and output SPI buffers need to be cleared and loaded respectively by the device SPI engine. Data is transferred between the input buffer and internal register buffers. The time required to perform this task is indicated by T_B , which is the time interval between the end of one byte transfer and the beginning of another. The recommended minimum time delay for T_B is 1 μ s. The number of bytes transferred depends on the register. It is important that the correct number of bytes is transferred for the associated register, because once the first byte (MSB) containing the device register address is received, the device will wait for the desired number of associated data bytes. The device will hang if an insufficient number of bytes are written to the register. To clear a hung condition, the device will need an external hard reset. The time required to process a command is also dependent on the command itself. Measured times for command completions are typically between 50 μ s to 300 μ s after reception.

5.3.1 Writing the SPI Bus

The SPI transfer size (in bytes) depends on the register being targeted. The first byte sent is the register address and subsequent bytes contain the data associated with the register. As data from the host is being transferred to the device via the MOSI line, data present on its SPI output buffer is simultaneously transferred back, MSB first, via the MISO line. The data returned is invalid for configuration registers. The following figure shows the contents of a single 3-byte SPI command written to the device. The Hardware Registers section provides information on the number of data bytes and their contents for an associated register. There is a minimum of 1 data byte for each register even if the data contents are "zeros".

23							15					7				0
	Register Address					Byt	e 1				Byt	e 0				



5.3.2 Reading the SPI Bus

Data is simultaneously read back during an SPI transfer cycle. Requested data from a prior command is available on the device SPI output buffers, and these are transferred back to the user host via the MISO pin. To obtain valid requested data would require querying the SERIAL_OUT_BUFFER, which requires 8 bytes or 64 clock cycles; 1 byte for the device register (0x37) and 7 empty bytes (MOSI) to clock out the returned data (MISO). An example of reading the device RF parameters (IF3 frequency) from the device is shown in the following figure.

the GET_DEVICE_PARAM register



Clock out the 6 bytes with write to the GET_SERIAL_OUT_BUFFER register (0x26)

Figure 10. Query example: Write followed by Read to the GET SERIAL BUFFER

In the figure above, the first transfer cycle is to make the request for IF3 frequency data through the GET_DEVICE_PARAM register. The subsequent cycle is to clock the data that was requested by sending 64 clocks into the GET_SERIAL_BUFFER register.

5.4 RS232 Interface

The RS232 version of the SC5310A has a standard interface buffered by an RS232 transceiver so that it may interface directly with many host devices, such as a desktop computer. The interface connector for RS232 communication is labeled "Digital I/O" on the front of the panel. Refer to *Table 3. Interface connector pin out description* for position and pin-out information. The RS232 device communication control set is provided in the following table.

Baud rate	Rate of transmission
	*Pin 16 of the Digital IO connector selects the rate. By default, if the pin is pulled high or open, the rate is set to 56700 at power up or upon HW reset. When the pin is pulled low or grounded, the rate is set to 115200 upon reset or power up.
Data bits	The number of bits in the data is fixed at 8.
Parity	Parity is 0 (zero)
Stop bits	1 stop bit
Flow control	0 (zero) or none

Table 9. RS232 Control Setting

Only 3-wire RS232 is required since hardware flow control is not used. These connections are the Tx, Rx, and Gnd. This interface is common on most host computers and microcontrollers, so user access to host ports is readily provided by the computer OS or microcontroller hardware registers.

5.4.1 Writing to the Device Via RS232

It is important that all necessary bytes associated with any one register are fully sent. In other words, if a register requires a total of 6 bytes (address plus data), then all 6 bytes must be sent even though the last byte may be null. The device, upon receiving the first register addressing byte, will wait for all the associated data bytes before acting on the register instruction. Failure to complete the register transmission will cause the device to behave erratically or hang. Information for writing to the configuration registers is provided in *Table 4. Configuration Registers*. Upon the

execution of the register that was sent, the device will return one (1) byte of data with bit 1 high to indicate success. This byte must be read by the host to clear its receive buffer so that reading subsequent registers will not contain corrupted data. Furthermore, reading back this byte will ensure that the device is ready for the next register command.

5.4.2 Reading from the Device Via RS232

To query information from the device, the query registers are addressed, and data is returned. *Table 5. Query Registers* contains the query register information. As with the configuration registers, it is important that all data byte(s) (write) associated with the query registers are sent even if they are null. All queries will return 8 bytes of data (read) with the first received byte being the most significant (MSB). Section *4.2 Query Registers* provides the format details of the received data.

5.5 PXI Express

The PXIe interface contains a high-speed PCIe-to-Serial bridge chip. This bridge chip communicates with the onboard microcontroller serially. The interface on the bridge chip resides at offset addresses between 0x00 and 0xFF from BARO; which is memory mapped. A kernel level driver for the operating system is needed to access this memory address. A simple driver using IO controls should be sufficient to read and write byte data to this block of addresses. Although SignalCore provides the driver and API for these products, information is provided here for users who may need to write drivers for a different operating system or a different driver. An example would be writing the API for the Linux operating system.

5.5.1 Setting Up the PCI to Serial Bridge

The serial function of the bridge chip must first be initialized before it can communicate with the onboard microcontroller, and hence communication between the microcontroller and the PXIe bus. The initialization can be done at the kernel level mode or at the user level mode, the decision is left to the user. The following table lists the programming order of the bridge register addresses to initialize and setup the serial port function.

Step	BARO Register Address	Data (Byte)
1	0x88	0x01
2	0x04	0x00
3	0x03	0x80
4	0x00	0x04
5	0x01	0x00
6	0x03	0x03
7	0x02	0x07

5.5.2 Writing to the Device

Bytes that are written to the device must go through the bridge chip. In this section, we will first look at the write cycle of each byte, and then the write cycle of each device register. Do note the difference between the bridge register addresses and the device register addresses.

5.5.2.1 Single Byte Write

The serial transfer buffer register address is located at 0x100 offset from BAR0 of the bridge chip, however, before writing byte data to this register, its status needs to be checked to confirm that it is ready to accept a new buffer set of bytes. The status register is located at 0x05; it must be read and bit 7 must be **high** to indicate that the transfer register is ready to receive the next byte buffer. Checking the status register of the serial bridge chip is required before every new command write.

5.5.2.2 Device Register Write

The process of writing the device registers is the same as writing an RS232 port, so the description of Section 5.4.1 Writing to the Device Via RS232 is applicable. Writing the device registers involves sending byte-by-byte data as described previously. Section 4.1 Configuration Registers provides information on the number of configuration write bytes needed for each device register. The first byte sent is the device register address, followed by the most significant byte of the register's associated data. When a device register is fully written, that is, all its data has been sent to the device, it will return 1 byte. This returned byte must be read (by the host) to clear the transfer buffer so that later received data are not corrupted. Section 5.5.3.1 Single Byte Read describes how a byte read cycle is performed.

5.5.3 Reading from the Device

Device data is passed back to the host via the bridge chip byte-by-byte. Details about a single byte read process and an entire register read process are explained in the following subsections.

5.5.3.1 Single Byte Read

The serial transfer buffer register address is located at 0x00 offset from BAR0 of the bridge chip. Before valid data can be read from the transfer register, its ready status must first be confirmed. The status register is located at 0x05; it must be read and bit 0 must be **high** to indicate that valid data is available. Checking the status register for available data is required before **every byte** read.

5.5.3.2 Device Register Read

After a write request to the device is made, 8 bytes of data is available to be read back. Use the single byte read process, as mentioned previously, to read all the bytes. See Section 4.2 for information of the exact number of request write bytes and the number of request read bytes, which is 8. All 8 bytes must be read to fully clear the transfer buffer; the first byte read is the most significant byte.

6 Calibration

6.1 Calibration EEPROM Map

Table 10 represents the EEPROM map of the device calibration values. All values are stored as littleendian 4-byte floating point numbers. Every point is 4-bytes long. Access to the data is possible through the CAL_EEPROM_READ register, which reads 8 bytes starting at the address pointed to by the register input.

Offset address	Points	Length (Bytes)	Data Type	Description						
0x00	664	664	U_8	Factory Reserved						
0x3F8	1	4	Float_32	Calibration temperature						
0x3FC	2	8	Float_32	Temp coeff C1, C2						
0x498	21	84	Float_32	IF3_response cal frequencies 5, 10, 15,,100, in MHz						
0x510	21	84	Float_32	IF3 relative gain response to the IF set for absolute RF gain measurement						
0x72C	30	120	Float_32	Relative If3_atten#1, 1-30 dB, 1 dB step						
0x7A4	30	120	Float_32	Relative If3_atten#2, 1-30 dB, 1 dB step						
0x938	1	4	Float_32	Relative IF2 Filt#1 gain						
0x93C	1	4	Float_32	Relative spectral inversion gain						
0x1A58	35	140	Float_32	RF cal freq, 5, 10, 20,90, 100, 200,300, 2500, in MHz						
Ox1AF8	35	140	Float_32	Absolute RF gain at each cal freq						
0x1B98	35	140	Float_32	Relative RF amp gain at each cal freq						
0x1C38	30x35	4200	Float_32	RF atten#1, 1-30 dB, 1 dB step for each freq a1_f0, a1_f1,,a1_fN a2_f0, a2_f1,,a2_fN a30_f0, a30_f1,,a30_fN Data is row catenated						
0x2EF8	30x35	4200	Float_32	RF atten#2, 1-30 dB, 1 dB step for each freq a1_f0, a1_f1,,a1_fN a2_f0, a2_f1,,a2_fN a30_f0, a30_f1,,a30_fN Data is row catenated						

Table 10. Calibration EEPROM Map

6.2 Absolute Conversion Gain

It is difficult to make gain measurements of every configuration setting of the downconverter as there are many combinations of attenuator and frequency settings, not to mention the various operating temperatures. However, the gain of the device can be computed to a reasonable level of accuracy with less data if the assumption is that every component setting is independent from one another. For example, assume the attenuator state of the IF3_ATTEN#1 does not affect the state of IF3_ATTEN#2, so with this independence there are only 2*30 attenuation measurements that need to be made; there is a mutually exclusive relationship. On the other hand, if they are not independent, for every setting of IF_ATTEN#1, 30 measurements are needed for IF3_ATTEN#2, bringing the total number of measurements to 30*30.

6.3 Gain Through the RF Conversion Path

Assuming independency, and to be able to compute the gain of the downconverter at any setting, an absolute reference state of the device must be determined first. Once this reference state is established, compensation can be applied to other relative configured states of the device. The established reference state of the device is as follows:

- All attenuators are set to 0 dB.
- IF2 Filter setting is 0.
- Inverted spectrum set to 0.
- RF amplifier disabled, set to 0.
- IF frequency is set at user specific setting or defaults to 50 MHz.
- RF is tuned to the list frequencies: 5, 10, 20, ..., 90, 100, 200, 300, ..., 2500 MHz.

The gain of the device in this state is measured at each frequency of the list. This set of measurements is the RF absolute gain stored at starting address 0x1B98 of the calibration EEPROM. Measurements taken for deviations from this reference setting are relative.

6.3.1 Applying Calibration

The amplifier gain, IF filter selections, and attenuator values are relative measurements from the absolute reference values made over various RF frequencies. These relative values are either subtracted (attenuation) or added (gain) to the absolute gain value to determine the gain of the relative configuration. For example, assume the RF_ATTEN#1 is at 20 dB, IF3_ATTEN#1 is at 10 dB, IF2_Filter bank is set to 1, IF3 frequency is set to 15 MHz, and the RF frequency is set to 1.550 GHz. A possible systematic approach would be:

- 1. Compute the relative RF Atten#1 value by interpolation because there is no measurement value at 1.55 GHz. A simple linear interpolation between the measured 1.5 GHz and 1.6 GHz values should provide a good estimate. A local spline interpolation over 5-6 surrounding points would provide better accuracy. Let us call this value rf_atten1 .
- 2. The IF3 Atten#1 attenuation value is read directly from memory: the 15th index of the attenuator array ATTEN3#1[15]. Let us call this correct attenuation value *if3_atten1*.

- 3. The IF response can also be read directly from memory, the 3^{rd} index (15 MHz/5 MHz) of the IF response array. Let us call this the *if* 3_*response*.
- 4. The IF2 filter gain is read directly from memory, which we shall call *if2_filter*.
- 5. The absolute gain at the frequency can be determined using interpolation between 2 absolute gain points, which we shall call G_{abs} .
- 6. The gain for this configuration is calculated using:

$$G = G_{abs} + if2_{filter} + if3_response - rf_{atten1} - if3_{atten1}$$

If the current device temperature is different from the calibration temperature, the gain correction due to temperature difference is computed using

$$\Delta G_{temp} = C_1 (T - T_0) + C_2 (T - T_0)^2 \, .$$

 ΔG_{temp} is the gain correction, C_1 and C_2 are the first and second order temperature gain coefficients respectively, and T and T_0 are the current temperature and calibration temperature respectively. Adding this correction to the previously calculated gain will compensate the value for temperature deviation.

$$G = G_{abs} + if2_{filter} + if3_{response} + \Delta G_{temp} - rf_{atten1} - if3_{atten1}$$

Revision Table

Revision	Revision Date	Description
1.0	8/10/18	Initial Release
1.1	2/26/19	Added feature to signal path register 16. Changed figure 6 to reflect latest conversion path implementation.
1.2	4/14/20	Updated tunable IF3 range.
2.0	8/13/20	Updated formatting.
2.1	12/8/22	Corrected torque range

